



Material Content Data Sheet



Sales Product Name		IPD60R600P7		Issued		24. January 2018		
MA#		MA001973462						
Package		PG-TO252-3-342		Weight*		333.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	0.50	0.50	4988	4988
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		480	
	non noble metal	copper	7440-50-8	160.096	47.97	48.03	479739	480363
	non noble metal	aluminium	7429-90-5	0.467	0.14	0.14	1400	1400
wire	non noble metal	aluminium	7429-90-5	0.467	0.14	0.14	1400	1400
encapsulation	organic material	carbon black	1333-86-4	1.167	0.35		3497	
	plastics	epoxy resin	-	16.340	4.90		48965	
	inorganic material	silicondioxide	60676-86-0	128.387	38.47	43.72	384721	437183
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11207	11207
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1569	1569
solder	non noble metal	tin	7440-31-5	0.038	0.01		115	
	noble metal	silver	7440-22-4	0.048	0.01		144	
	non noble metal	lead	7439-92-1	1.832	0.55	0.57	5489	5748
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		58	
	non noble metal	copper	7440-50-8	19.177	5.75	5.76	57467	57542
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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